

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	"20040051178"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 09:41
S2	4	"6657305"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 09:45
S3	1	"6153935".PN.	USPAT	OR	OFF	2004/10/05 09:41
S4	1	"6207556".PN.	USPAT	OR	OFF	2004/10/05 09:42
S5	1	"6245665".PN.	USPAT	OR	OFF	2004/10/05 09:42
S6	1	"6245683".PN.	USPAT	OR	OFF	2004/10/05 09:43
S7	1	"6294835".PN.	USPAT	OR	OFF	2004/10/05 09:43
S8	1	"6329701".PN.	USPAT	OR	OFF	2004/10/05 09:43
S9	1	@ad<="20001101" and 'interconnect' and 'recessed mask'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 11:41
S10	451	@ad<="20001101" and 'interconnect' and 'low k' and 'mask'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 09:56
S11	76	@ad<="20001101" and 'interconnect' same 'low k' same 'mask'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 10:28
S12	11	@ad<="20001101" and 'recessed mask'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 10:27
S13	71	@ad<="20001101" and 'interconnection' and 'mask layer' and 'cap layer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 11:52
S14	5	@ad<="20001101" and 'interconnection' and 'prevent' same 'high electrical fields'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 10:50
S15	6	@ad<="20001101" and 'low k' and 'Si' adj1 'C' adj1 'H' and 'cap'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 10:55

S16	8	@ad<="20001101" and 'Si' adj1 'C' adj1 'H' and 'cap'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 10:55
S17	1	@ad<="20001101" and 'Si:C:H' and 'cap'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 10:55
S18	26	@ad<="20001101" and 'Si' adj1 'C' adj1 'H' and 'mask'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 11:03
S19	29	@ad<="20001101" and 'damascene' and 'low-k' and 'hardmask'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 11:04
S20	355	@ad<="20001101" and (438/623). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 11:45
S21	2507	@ad<="20001101" and (438/624). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 12:09
S22	247	@ad<="20001101" and (438/625). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 11:46
S23	324	@ad<="20001101" and (438/626). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 11:46
S24	466	@ad<="20001101" and (438/627). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 11:47
S25	153	@ad<="20001101" and (438/628). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 11:47
S26	954	@ad<="20001101" and (438/643). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 11:48

S27	180	@ad<="20001101" and (438/644). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 11:47
S28	150	@ad<="20001101" and (438/645). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 11:48
S29	1503	@ad<="20001101" and (438/690-692).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 11:49
S30	1136	@ad<="20001101" and (438/637). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 12:09
S31	402	@ad<="20001101" and (438/397). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 11:50
S32	1	"5893752".PN.	USPAT	OR	OFF	2004/10/05 11:50
S33	1	"5206187".PN.	USPAT	OR	OFF	2004/10/05 11:50
S34	1	"5880018".PN.	USPAT	OR	OFF	2004/10/05 11:51
S35	1	"5721167".PN.	USPAT	OR	OFF	2004/10/05 11:52
S36	1	"5612254".PN.	USPAT	OR	OFF	2004/10/05 11:52
S37	1	"5506177".PN.	USPAT	OR	OFF	2004/10/05 11:52
S38	218	@ad<="20001101" and 'interconnection' same 'undercut'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 11:53
S39	0	@ad<="20001101" and 'low k' and 'interconnection' same 'undercut'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 11:53
S40	58	@ad<="20001101" and 'dielectric' and 'interconnection' same 'undercut'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 12:05
S41	141	@ad<="20001101" and 'copper' same 'interconnection' and 'diffusion barrier' and 'low dielectric'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 11:47

S42	58	@ad<="20001101" and 'copper' same 'interconnection' and 'diffusion barrier' and 'low dielectric' and 'mask'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 12:07
S43	483	@ad<="20001101" and (438/633). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 12:09
S44	360	@ad<="20001101" and (438/638). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/05 12:10
S45	80	@ad<="20001101" and 'copper' same 'interconnection' and 'diffusion barrier' and 'low dielectric' and 'seed'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 12:03
S46	1	"6184138".PN.	USPAT; USOCR	OR	ON	2005/10/05 11:53
S47	1	"6146988".PN.	USPAT; USOCR	OR	ON	2005/10/05 11:53
S48	1	"6037664".PN.	USPAT; USOCR	OR	ON	2005/10/05 11:54
S49	1	"5969422".PN.	USPAT; USOCR	OR	ON	2005/10/05 11:55
S50	1	"5693563".PN.	USPAT; USOCR	OR	ON	2005/10/05 11:55
S51	1	"5447887".PN.	USPAT; USOCR	OR	ON	2005/10/05 11:55
S52	1	"6117785".PN.	USPAT; USOCR	OR	ON	2005/10/05 12:00
S53	1	"6080663".PN.	USPAT; USOCR	OR	ON	2005/10/05 12:00
S54	1	"6074942".PN.	USPAT; USOCR	OR	ON	2005/10/05 12:00
S55	99	@ad<="20001101" and 'interconnection' and 'diffusion barrier' and 'low dielectric' and 'seed' same 'copper'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 12:49
S56	35	@ad<="20001101" and 'interconnection' and 'TiN' and 'low k' and 'seed' same 'copper'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 12:03
S57	1	"6211056".PN.	USPAT; USOCR	OR	ON	2005/10/05 12:05
S58	1	"6201303".PN.	USPAT; USOCR	OR	ON	2005/10/05 12:05
S59	1	"6159845".PN.	USPAT; USOCR	OR	ON	2005/10/05 12:05

S60	1	"6150268".PN.	USPAT; USOCR	OR	ON	2005/10/05 12:06
S61	1	"6110792".PN.	USPAT; USOCR	OR	ON	2005/10/05 12:06
S62	1	"6046108".PN.	USPAT; USOCR	OR	ON	2005/10/05 12:08
S63	1	"6015749".PN.	USPAT; USOCR	OR	ON	2005/10/05 12:08
S64	1	"5969422".PN.	USPAT; USOCR	OR	ON	2005/10/05 12:08
S65	1	"5891513".PN.	USPAT; USOCR	OR	ON	2005/10/05 12:08
S66	1	"5824599".PN.	USPAT; USOCR	OR	ON	2005/10/05 12:08
S67	1	"5780908".PN.	USPAT; USOCR	OR	ON	2005/10/05 12:08
S68	1	"5731245".PN.	USPAT; USOCR	OR	ON	2005/10/05 12:08
S69	73	@ad<="20001101" and 'interconnection' and 'diffusion barrier' and 'etch stop' and 'seed' same 'copper'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 12:50
S70	1	"6329701".PN.	USPAT; USOCR	OR	ON	2005/10/05 13:03
S71	1	"6294835".PN.	USPAT; USOCR	OR	ON	2005/10/05 13:04
S72	1	"6294835".PN.	USPAT; USOCR	OR	ON	2005/10/05 13:04
S73	1	"6245683".PN.	USPAT; USOCR	OR	ON	2005/10/05 13:07
S74	1	"6245665".PN.	USPAT; USOCR	OR	ON	2005/10/05 13:08
S75	1	"6207556".PN.	USPAT; USOCR	OR	ON	2005/10/05 13:08
S76	1	"6153935".PN.	USPAT; USOCR	OR	ON	2005/10/05 13:08
S77	1	"6004188".PN.	USPAT; USOCR	OR	ON	2005/10/05 13:09
S78	1	"5817572".PN.	USPAT; USOCR	OR	ON	2005/10/05 13:09
S79	1	"5708303".PN.	USPAT; USOCR	OR	ON	2005/10/05 13:09
S80	2	("6133139").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/05 13:14